

In re the Application of
Yoshikazu KASUYA

Serial No.: 09/963,924

Filing Date: Sept. 26, 2001

For: METHODS FOR MANUFACTURING
SEMICONDUCTOR DEVICES AND
SEMICONDUCTOR DEVICES



Group Art Unit: 2814

Examiner: Rao, S.

ASSISTANT COMMISSIONER OF PATENTS
Washington, D.C. 20231

Sir:

Transmitted herewith is an Amendment in the above-identified application.

- Small entity status of this application under 37 CFR 1.9 and 1.27 has been established by a verified statement previously submitted.
- A verified statement to establish small entity status under 37 CFR 1.9 and 1.27 is enclosed.
- No additional fee is required.

The fee has been calculated as shown below:

	CLAIMS REMAINING AFTER AMENDMENT		HIGHEST NO PREVIOUSLY PAID FOR		PRESENT EXTRA RATE		ADDIT. FEE	OR	RATE		ADDIT. FEE
TOTAL	22	MINUS	21	=	1	x	\$9	OR	x 18		\$ 18
INDEP CLAIMS *	3	MINUS	5	=	0	x	\$42	OR	x 84		\$0
— FIRST PRESENTATION OF MULTIPLE DEP. CLAIM						+	\$	OR	+ 270		\$0
					TOTAL		\$0	OR	TOTAL		\$ 18

— Please charge Deposit Account No. 50-0585 the amount of \$___ to cover the extension fee and also the amount of \$___ to cover the claim fee. A duplicate copy of this sheet is enclosed.

— A check in the amount of \$___ to cover the extension fee is enclosed.

X A check in the amount of \$ 18 to cover the filing fee for additional claims is enclosed.

X The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. No. 50-0585. A duplicate of this sheet is enclosed.

X Any filing fees under 37 CFR 1.16 for the presentation of extra claims.

X Any patent application processing fees under 37 CFR 1.17.

Respectfully submitted,

Alan S. Raynes

Dated: February 21, 2003

Alan S. Raynes

Registration No. 39,809

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I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231 on Feb. 21, 2003.

Alan S. Raynes
Alan S. Raynes

2/21/03
Date

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AMENDMENT

Assistant Commissioner for Patents
Washington, DC 20231

Dear Sirs:

In response to the Office Action dated Nov. 21, 2002, the response being due by Feb. 21, 2003, please enter and consider the following.

IN THE SPECIFICATION:

On page 1, please delete the first paragraph and insert the following in its place:

B1 --Applicant hereby incorporates by reference Japanese Application No. 2000-292143, filed September 26, 2000, in its entirety. Applicant hereby incorporates by reference U.S. Application Serial No. 09/963,168 in its entirety. Applicant hereby incorporates by reference U.S. Application Serial No. 09/963,903 in its entirety.--

IN THE CLAIMS:

Please amend claims 1, 3 and 5-17 as follows:

- B2 1. (amended) A method for manufacturing a semiconductor device, the method comprising the steps of:
- (a) forming a gate dielectric layer;
 - (b) forming a first conductive layer on the gate dielectric layer;

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